IEEE EPS in Advanced Packaging Sharing for Santa Clara US

Dec 20th, 2024

Minutes from December 20, 2024 meeting

Attendees:
Luu, Masha, Joshua, Eugene, YY Tan, Megan, Xiaoling, Angelique, Ou

New Introduction:

1. Meghan Hauser from Booz Allen Hamilton
2. Angelique Raley from Tokyo Electron (TEL)
   https://drive.google.com/drive/folders/1P--rJCLoJLwRlcWZ_AUkG2QGmx4PlAoj

Special Speaker:

1. Yik Yee Tan from The Yole Group Malaysia gave a great update on the state of advanced packaging (AP). One of the key take aways was that currently AP is only 5% of the packaging market and will remain around 5% of the market in 2030, the revenue from AP is currently 47% of the market and by 2030 that percentage goes up to 54%. So even though it is a small fraction of the market, if you are an OSAT or foundry, the profits from AP will drive further advances in packaging.

- **IEEE EPS Santa Clara has invited Dr. Tan Yik Yee to share on "Advanced Packaging focusing on 2.5D/3D packaging" to Emerging Technology Committees. The committee members are diverse and covers across majority of the supply chain of the electronics industry.**
- **The participants have actively participated in the Q&A session especially on the advanced packaging readiness for Generative AI, including how the cost and thermal management are being addressed.**
- **Total 9 participants attended the sharing.**

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